

ABSTRACT

The present invention relates to the industrial field of semiconductor manufacture. The present invention provides a method for chemically processing a surface of a semiconductor substrate comprising the steps of: placing a semiconductor substrate (4) above a chemical solution (5) by a shaft (2) and making the lower surface of the semiconductor substrate (4) be at a certain distance from the liquid surface of the chemical solution (5); and jetting the chemical solution onto the lower surface of the semiconductor substrate by a jet apparatus (3) to perform the chemical processing on the lower surface, and a device for the same including a chemical tank (1) containing a chemical solution, a shaft (2) for supporting the semiconductor substrate (4) above the chemical solution, and a jet apparatus (3) for jetting the chemical solution onto the lower surface of the semiconductor substrate (4). The method may perform a chemical treatment on one side of a semiconductor substrate without any protection for the other side.



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